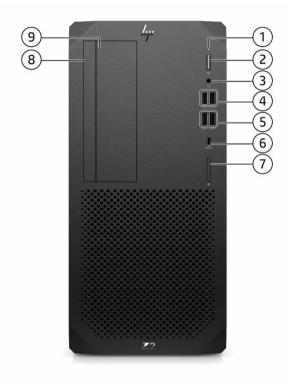
Overview

HP Z2 Tower G8 Workstation



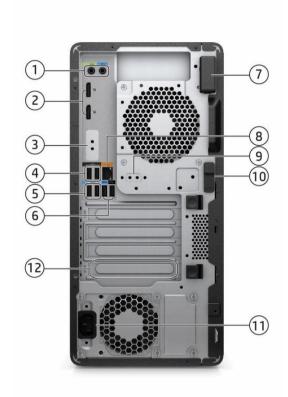
front

- 1. HDD Activity LED
- 2. Power button
- 3. Universal audio jack (with CTIA & OMTP headset support)
- 4. (2) Type-A SuperSpeed USB 5Gbps signaling rate port (1 charge port 9. supports up to 5V/2.1A)
- 5. (2) Type-A SuperSpeed USB 10Gbps signaling rate port

- 6. (1) Type-C® SuperSpeed USB 20Gbps signaling rate port (optional, charge supports up to 5V/3A)
- 7. SD card reader 4.0 (optional)
- 8. Slim ODD bay
- 9. External 5.25" bay



Overview



rear

- (1) Audio Line-in jack
 (1) Audio Line-out jack
- (2) DisplayPort 1.4
- 3. Flex I/O module: choose one from the following:
 (1) DisplayPort 1.4, (1) HDMI 2.0b, (1) VGA, (1) Dual Type-A
 SuperSpeed USB 5Gbps signaling rate port, (1) Type-C®
 SuperSpeed USB 10Gbps signaling rate port (Power Delivery
 15W, Alt Mode DisplayPort), (1) 2nd GbE LAN, (1) Thunderbolt 3
 with Type-C® SuperSpeed USB4 40Gbps signaling rate* (cabled to PCIe AIC)
- 4. (2) Hi-Speed USB 480Mbps signaling rate port
- 5. (2) Type-A SuperSpeed USB 10Gbps signaling rate port

- 6. (1) Type-A SuperSpeed USB 5Gbps signaling rate port (1) Hi-Speed USB 480Mbps signaling rate port
- 7. WLAN Antenna (optional)
- 8. RJ-45
- 9. 2nd serial port (optional)
- 10. Release latch
- 11. Power connector
- 12. Type-C[®] Thunderbolt[™] 3 port (optional)

*Maximum speed requires DisplayPort™ and PCIe aggregation.

Tower

NOTE: All onboard Display support DP1.4/HBR2 when video output is via Intel Graphics.

NOTE: Flex I/O module Display support DP1.4/HBR3, resolution support up to 5120x3200 24bpp @60Hz

NOTE: TBT 3 will be available in Q3, 2021

Form Factor

Operating Systems Preinstalled:

- Windows 11 Pro²
- Windows 11 Pro for Workstations²
- Windows 11 Home HP recommends Windows 11 Pro for business²
- Windows 10 Pro^{1,2}
- Windows 10 Pro for Workstations^{1,2}



Overview

- Windows 10 Home HP recommends Windows 11 Pro for business^{1,2}
- Linux®-ready³
- Ubuntu Linux 20.04 LTS⁴
- Red Hat® Enterprise Linux® (RHEL) Workstation paper license (1 yr) only (not preinstalled)
- WSL2**

Web-supported only:

Windows 10 Enterprise 64²

Supported Version:

 HP tested Windows 10, versions 1909, 2004, and 20H2 on this platform. For testing information on newer versions of Windows 10, please see: https://support.hp.com/document/c05195282.

¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

Processors

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	Hyper- Threading	Integrated Graphics	Intel® Turbo Boost Technology³	Featuring Intel® vPro® Technology⁴	16GB Intel® Optane™ memory²	TDP (W)
Intel® Core™ i9 11900K Processor	8	3.5	16	3200	TRUE	Intel® UHD Graphics 750	5.2	TRUE	Υ	125
Intel® Core™ i9 11900F Processor	8	2.5	16	3200	TRUE	N/A	5.2	N/A	Υ	65
Intel® Core™ i9 11900 Processor	8	2.5	16	3200	TRUE	Intel® UHD Graphics 750	5.2	TRUE	Υ	65
Intel® Core™ i7 11700K Processor	8	3.6	16	3200	TRUE	Intel® UHD Graphics 750	5	TRUE	Υ	125
Intel® Core™ i7 11700 processor	8	2.5	16	3200	TRUE	Intel® UHD Graphics 750	4.9	TRUE	Υ	65
Intel® Core™ i5 11600K processor	6	3.9	12	3200	TRUE	Intel® UHD Graphics 750	4.9	TRUE	Υ	125
Intel® Core™ i5 11600 processor	6	2.8	12	3200	TRUE	Intel® UHD Graphics 750	4.8	TRUE	Υ	65



³ For detailed Linux® OS/hardware information, see: http://www.hp.com/support/linux_hardware_matrix

⁴ Ubuntu Linux 20.04 LTS available Q3, 2021

Overview

Intel® Core™ i5 11500 processor	6	2.7	12	3200	TRUE	Intel® UHD Graphics 750	4.6	TRUE	Y	65
Intel® Core™ i5 11400F processor	6	2.6	12	3200	TRUE	N/A	4.4	N/A	Y	65
Intel® Core™ i5 11400 processor	6	2.6	12	3200	TRUE	Intel® UHD Graphics 730	4.4	N/A	Y	65
Intel® Xeon® W- 1390P processor	8	3.5	16	3200	TRUE	Intel® UHD Graphics	5.2	TRUE	Υ	125
Intel® Xeon® W- 1390 processor	8	2.8	16	3200	TRUE	Intel® UHD Graphics	5.1	TRUE	Y	80
Intel® Xeon® W- 1370P processor	8	3.6	16	3200	TRUE	Intel® UHD Graphics	5.2	TRUE	Y	125
Intel® Xeon® W- 1370 processor	8	2.9	16	3200	TRUE	Intel® UHD Graphics	5.1	TRUE	Y	80
Intel® Xeon® W- 1350P processor	6	4	12	3200	TRUE	Intel® UHD Graphics	5.1	TRUE	Y	125
Intel® Xeon® W- 1350 processor	6	3.3	12	3200	TRUE	Intel® UHD Graphics	5	TRUE	Υ	80

- 1. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 2. Intel® Optane™ memory is sold separately. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Available for HP commercial desktops and notebooks and for select HP workstations (HP Z240 Tower/SFF, Z2 Mini, ZBook Studio, 15 and 17 G5) and requires a SATA HDD, 7th Gen or higher Intel® Core™ processor or Intel® Xeon® processor E3-1200 V6 product family or higher, BIOS version with Intel® Optane™ supported, Windows 10 version 1703 or higher, M.2 type 2280-S1-B-M connector on a PCH Remapped PCIe Controller and Lanes in a x2 or x4 configuration with B-M keys that meet NVMeTM Spec 1.1, and an Intel® Rapid Storage Technology (Intel® RST) 15.5 driver.
- 3. The specifications shown in the Intel® Turbo Boost Technology column represent the maximum turbo frequency with one core active. Turbo boost stepping occurs in 100MHz increments. Processors that do not have turbo functionality are denoted as N/A. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information
- 4. For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See http://intel.com/vpro

ColorBlackConvertibilityNoExpansion Slots (see
system board section forSlot 1:
PCIe Gen4 x16

Slot 2:

PCle Gen3 x1 - with x4 Connector

Slot 3:

PCIe Gen3 x4 - with x16 Connector



more details)

Overview

Slot 4: PCIe Gen3 x4

Expansion Bays (see

(2) Internal 3.5" bays storage section for more (1) External 5.25" bay

details)

(1) Internal 2.5" bay (for SSD only)

(1) Dedicated 9.5mm slim optical disk drive bay

Front I/O

(2) Type-A SuperSpeed USB 5Gbps signaling rate port (1 charge port supports up to 5V/2.1A), (2) Type-A SuperSpeed USB 10Gbps signaling rate port, (1) Type-C SuperSpeed® USB 20Gbps signaling rate port (charge supports up to 5V/3A, optional), (1) SD card reader (optional), (1) universal audio jack

Internal I/O

(1) Hi-Speed USB 480Mbps signaling rate port

(1) serial port

Rear I/O

(2) DisplayPort 1.4*, (1) Audio Line out, (1) Audio Line in, (1) RJ-45, (3) Hi-Speed USB 480Mbps signaling rate port. (2) Type-A SuperSpeed USB 10Gbps signaling rate port. (1) Type-A SuperSpeed USB 5Gbps signaling rate port, (1) serial (optional),

(1) Flex I/O port (VGA, HDMI 2.0b, DisplayPort 1.4, Type-C® SuperSpeed USB 10Gbps signaling rate port (Power Delivery 15W, Alt Mode DisplayPort), Dual Type -A SuperSpeed USB 5Gbps signaling rate port, 2nd 1GbE LAN, Thunderbolt 3** with SuperSpeed USB4 Type-C® 40Gbps signaling rate*** (cabled to PCIe AIC))

*All onboard Display support DP1.4/HBR2 when video output is via Intel Graphics.

**TBT 3 will be available in 03. 2021. About Thunderbolt compatibility, please refer to the

FAQ of Thunderbolt community. https://www.thunderbolttechnology.net/tech/faq

***Maximum speed requires DisplayPort™ and PCIe aggregation.

Interfaces Supported

SD card reader (optional)

On-board RAID Support RAID 0

RAID 1

Chassis Dimensions (H x H: 14" [356mm]

WxD)

W: 6.7" [169mm]

D: 15.2" [385mm]

Packaged Dimensions

H: 20.39" (518mm) W: 11.61" (295mm) D: 19.29" (490mm)

Rack Dimensions

Weight

Exact weights depend upon configuration (System weight only).

Starting at 7kg (15.43lbs.)

Temperature

Operating: 5° to 35° C (40° to 95° F)

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for

every 305 m (1,000 feet) increase in elevation Non-operating: -40° to 60° C (-40° to 140° F)

Maximum rate of change: 10°C/hr

Humidity

Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

pressurized)6

Maximum Altitude (non- Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Temperature for details.

Power Supply

700W wide-ranging, active Power Factor Correction, 92% Efficiency, 500W wide-ranging, active Power Factor Correction, 90% Efficiency, 350W wide-ranging, active Power Factor Correction, 92% Efficiency.

Overview

NOTE: The Power Supply Efficiency Report for the 700W 92% Efficiency, 500W 90% Efficiency and 350W 92% Efficiency Power Supply may be found at the following links:

700W PSU:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

500W PSU:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

350W PSU:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

Backup Devices For a complete listing of compatible DAT tape drives, LTO tape drives and RDX Removable Disk Backup

System offerings, please visit http://www.hp.com/go/connect

Chipset Intel® W580 chipset

Memory 4 DIMM slots, supporting up to 128GB ECC/non-ECC, and up to DDR4 3200 MT/s speed



Supported Components

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	11th Generation Intel® Core™ Processors*				
	Intel® Core™ i9 11900K Processor	Υ	N		
	Intel® Core™ i9 11900F Processor	Υ	N		1
	Intel® Core™ i9 11900 Processor	Υ	N		
	Intel® Core™ i7 11700K Processor	Υ	N		
	Intel® Core™ i7 11700 processor	Υ	N		
	Intel® Core™ i5 11600K processor	Υ	N		
	Intel® Core™ i5 11600 processor	Υ	N		
	Intel® Core™ i5 11500 processor	Υ	N		
	Intel® Core™ i5 11400F processor	Υ	N		1
	Intel® Core™ i5 11400 processor	Υ	N		
	Intel® Xeon® W Processors				
	Intel® Xeon® W-1390P processor	Υ	N		
	Intel® Xeon® W-1390 processor	Υ	N		
	Intel® Xeon® W-1370P processor	Υ	N		
	Intel® Xeon® W-1370 processor	Υ	N		
	Intel® Xeon® W-1350P processor	Υ	N		
	Intel® Xeon® W-1350 processor	Υ	N		
	* These processors support only non-ECC memory				

SATA Hard Drives Factory Option Kit Part Configured Option Kit Number

1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

500GB SATA 7200 rpm 6Gb/s 3.5" HDD

1TB SATA 7200 rpm 6Gb/s 3.5" HDD

2TB SATA 7200 rpm 6Gb/s 3.5" HDD

500GB SATA 7.2K SED SFF HDD

NOTE 1: No iGfx. A discrete graphics card must be purchased at the same time.

PCIe Solid State Drives

HP ZTurbo PCIE-4X4 1TB TLC Z2 G8 TWR/SFF SSDKit	Υ	Υ	201F5AA/AT
HP ZTurbo PCIE-4X4 256GB SED Z2 G8 TWR/SFF SSDKit	Υ	Υ	201F6AA
HP ZTurbo PCIE-4X4 256GB TLC Z2 G8 TWR/SFF SSDKit	Υ	Υ	201F7AA/AT
HP ZTurbo PCIE-4X4 2TB TLC Z2 G8 TWR/SFF SSDKit	Υ	Υ	201F8AA
HP ZTurbo PCIE-4X4 512GB SED Z2 G8 TWR/SFF SSDKit	Υ	Υ	201F9AA
HP ZTurbo PCIE-4X4 512GB TLC Z2 G8 TWR/SFF SSDKit	Υ	Υ	201G0AA/AT
Z Turbo 1TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC			
M.2 Z2 SSD	Υ	Υ	223A3AA/AT

Υ

Υ

Υ

Υ

Υ

Υ

Υ

Υ

Υ

Υ



LQ036AA

LQ037AA

TBD

WOR10AA

2Z274AA

K4T76AA

2Z273AA

D8N29AA

Supported Components

Z Turbo 2TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD

Y Y 223A4AA/AT

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB is reserved for system recovery software.

Hard Drive Controllers		Factory Configured	Option Kit
	Integrated SATA Controller (Z2 G8)		
	Integrated SATA Controller, RAID 0,1 supported: 4x 6 Gb/s ports	Υ	
	Factory integrated RAID on motherboard for SATA drives		
	RAID 0 Data Configuration	Υ	
	RAID 1 Data Configuration	Υ	
	Factory integrated RAID on motherboard for Z Turbo Drive		
	RAID 0 Data Configuration	Υ	
	RAID 1 Data Configuration	Υ	
	NOTE: CATA bardware BAID is not supported on Linux® sustame	The Linux® kernel with	huilt in

NOTE: SATA hardware RAID is not supported on Linux® systems. The Linux® kernel, with built-in software RAID, provides excellent functionality and performance. It is a good alternative to hardware-based RAID. All drives must be identical in type and capacity. Boot volume/RAID array must be less than 2 TB

NOTE: Requires identical drives (speeds, capacity, and interface).

NOTE: The HP Z2 Tower G8 Workstation is capable of configuring up to 2 Z Turbo Drives. By default, the Z Turbo Drive configured will be installed in the M.2 storage slot on the system's motherboard. **NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows 10) of system disk is reserved for system recovery software.

NOTE: In order to configure Z Turbo Drive RAID, the first SSD must be installed in the PCH connected M.2 slot and the second SSD must be installed in a PCIe add in card. This is automatically configured when Z Turbo RAID is selected at time of system purchase.

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards
Graphics Cable Adapters	HP DisplayPort To HDMI True 4k Adapter	Υ	Υ	2JA63AA	
	HP Single miniDP-to-DP Adapter Cable	Υ	Υ	2MY05AA	
	HP DisplayPort To DVI-D Adapter	Υ	Υ	FH973AA	
	HP DisplayPort To VGA Adapter	Υ	Υ	AS615AA	
	HP USB-C to DisplayPort Adapter	Υ	Υ	4SH08AA	
	HP USB-C to HDMI Adapter	Υ	Υ	4SH07AA	
	HP USB-C to VGA Adapter	Υ	Υ	4SH06AA	
Entry 3D	NVIDIA® Quadro® P400 2GB Graphics	Υ	Υ	1ME43AA/AT	2
	NVIDIA® T400 2 GB GDDR6 LP Blower Fan 3mDP PCIe x16 Graphics	Υ	Υ	340K8AA	2
	NVIDIA® T600 4 GB GDDR6 LP Blower Fan 4mDP PCIe x16 Graphics	Υ	Υ	340K9AA	2
Mid-range 3D	AMD Radeon™ Pro WX 3200 4GB Graphics	Υ	Υ	6YT68AA/AT	2
	NVIDIA® T1000 4GB Graphics	Υ	Υ	20X22AA/AT	2
	NVIDIA RTX A2000 6 GB GDDR6 Blower Fan 4mDP PCIe x16 Graphics	Υ	Υ	340L0AA	1



Supported Components

	AMD Radeon™ RX 6700 XT 12GB Graphics	Υ	N		1
High-End 3D	NVIDIA® RTX® A4000 16GB Graphics**	Υ	Υ	20X24AA/AT	1
	NVIDIA® RTX A4500 20 GB GDDR6 4DP Graphics**	Υ	Υ	5S458AA/AT	1
	AMD Radeon™ Pro W5500 8GB Graphics**	Υ	Υ	9GC16AA/AT	1
	AMD Radeon™ Pro W5700 8GB Graphics**	Υ	Υ	9GC15AA/AT	1
Ultra High-End 3D	NVIDIA® RTX® A5000 24GB Graphics*	Υ	Υ	20X23AA/AT	1
	AMD Radeon Pro W6600 8 GB GDDR6 4DP Graphics	Υ	Υ	340K5AA	1
	AMD Radeon Pro W6800 32 GB GDDR6 6mDP Graphics	Υ	Υ	340K7AA	1

^{*} Requires 700W chassis.

NOTE: NVIDIA® RTX A5000, NVIDIA® RTX A4000, NVIDIA® T1000 will be available in Q3, 2021

Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP 4GB (1x4GB) DDR4-3200 nECC UDIMM	γ	γ	141J1AA/AT	2,4
	HP 8GB (2x4GB) DDR4-3200 nECC UDIMM	Y	N		_, .
	HP 8GB (1x8GB) DDR4-3200 nECC UDIMM	Υ	Υ	141J4AA/AT	2,4
	HP 8GB (1x8GB) DDR4-3200 ECC UDIMM	Υ	Υ	141J3AA/AT	1,2,4
	HP 16GB (2x8GB) DDR4-3200 nECC UDIMM	Υ	N		
	HP 16GB (2x8GB) DDR4-3200 ECC UDIMM	Υ	N		1
	HP 16GB (1x16GB) DDR4-3200 nECC UDIMM	Υ	Υ	141H3AA/AT	2,4
	HP 16GB (1x16GB) DDR4-3200 ECC UDIMM	Υ	Υ	141H2AA/AT	1,2,4
	HP 24GB (3x8GB) DDR4-3200 nECC UDIMM	Υ	N		
	HP 24GB (3x8GB) DDR4-3200 ECC UDIMM	Υ	N		1
	HP 32GB (4x8GB) DDR4-3200 nECC UDIMM	Υ	N		3
	HP 32GB (4x8GB) DDR4-3200 ECC UDIMM	Υ	N		1,3
	HP 32GB (2x16GB) DDR4-3200 nECC UDIMM	Υ	N		
	HP 32GB (2x16GB) DDR4-3200 ECC UDIMM	Υ	N		1
	HP 32GB (1x32GB) DDR4-3200 nECC UDIMM	Υ	N	141H9AA	2, 4
	HP 32GB (1x32GB) DDR4-3200 ECC UDIMM	Υ	Υ	141H7AA	1, 2, 4
	HP 64GB (4x16GB) DDR4-3200 nECC UDIMM	Υ	N		3
	HP 64GB (4x16GB) DDR4-3200 ECC UDIMM	Υ	N		1,3
	HP 64GB (2x32GB) DDR4-3200 nECC UDIMM	Υ	N		3
	HP 64GB (2x32GB) DDR4-3200 ECC UDIMM	Υ	N		1,3
	HP 128GB (4x32GB) DDR4-3200 nECC UDIMM	Υ	N		3
	HP 128GB (4x32GB) DDR4-3200 ECC UDIMM	Υ	N		1,3

NOTES:

- 1. Intel® Xeon® can support either ECC or non-ECC memory; Intel® Core™ i5/i7/i9 processors only support non-ECC memory.
- 2. Two channels of DDR4 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.
- 3. The maximum speed supported by Intel on this configuration is 2933 MT/s



^{**} Requires at least 500W chassis.

Supported Components

4. For Option Kits, only 2666Mhz can be guaranteed.

NOTE: When more than one memory slot is populated, symmetric configurations are required for 2 DIMMs per channel. Mix of different part numbers or mix of single and dual ranks within a channel is not allowed.

Optical and Removable Storage		Factory Configured	Option Kit	Option Kit Part Number
	HP 9.5mm Slim DVD Writer	Υ	Υ	4L5K0AA
	HP DX175 Removable HDD Frame/Carrier	Υ	Υ	1ZX71AA
	HP DX175 Removable HDD Spare Carrier	Υ	Υ	1ZX72AA
	HP SD card reader Z2 TWR	Υ	Υ	141K3AA/AT
	HP 9.5mm Slim DVD-ROM Drive	Υ	Υ	4L5K1AA
	HP QX310 5.25 in Frame/Carrier	Υ	Υ	4Y7D9AA

NOTE: With Blu-ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number
	Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro® with Intel® AMT 15.0)	Υ	N	
	HP 1GbE LAN Flex Port 2020	Υ	Υ	141J6AA/AT
	Aquantia AQN108 1-Port 5GbE NIC	Υ	Υ	1PM63AA
	Intel Ethernet 1350-T4 4-Port 1Gb NIC	N	Υ	W8X25AA
	Intel X550 10GBASE-T Dual Port NIC	Υ	Υ	1QL46AA
	Intel Ethernet Network Adapter I225-T1*	Υ	Υ	406L9AA
	Intel Ethernet I350-T2 2-Port 1Gb NIC	Υ	Υ	V4A91AA
	Intel Wi-Fi 6 AX201 BT5 M.2 non-vPro**	Υ	N	
	Intel Ethernet I210-T1 PCIe NIC	Υ		

^{*}Planned to be available in Q3,2021

NOTE: The integrated network connection is required to support Intel® vPro® Technology.

NOTE: If AMT is provisioned, then network teaming with the integrated LAN port is not possible.

NOTE: "Gigabit" Ethernet indicates compliance with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.



^{**}Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

Supported Components

Input Devices		Factory Configured	Option Kit	Option Kit Part Number
	HP Premium Wireless Keyboard	Y	Υ	Z9N41AA/AT
	HP USB 320K Keyboard	Υ	Υ	9SR37AA
	HP USB Business Slim Wired SmartCard CCID Keyboard	Υ	N	
	HP PS/2 Business Slim Keyboard	N	Υ	N3R86AA
	HP USB Premium Wired Keyboard PROMO	Υ	Υ	Z9N40AT
	HP 320M Wired Mouse	Υ	Υ	9VA80AA
	HP USB Premium Mouse	Υ	Υ	1JR32AA
	HP Wireless Premium Mouse	Υ	Υ	1JR31AA
	HP Promo PS/2 Mouse	N	Υ	QY775AT
	HP Wired Desktop 320MK Mouse and Keyboard	N	Υ	9SR36AA
	HP Creator 935 Black Wireless Mouse	N	Υ	1D0K8AA
Other Hardware		Factory Configured	Option Kit	Option Kit Part Number
	HP Single TBT3 Type C and USB4 PCIe x4 Card1	Y	N	
	HP Z2 Internal Serial Port and PS/2 Port	Υ	Υ	141K9AA/AT
	HP Z2 Power Cord Kit	Y	Y	1N1D5AA
	HP Z2 2nd serial port adapter	Y	Y	141K8AA/AT
	HP Z2 Tower Dust Filter	Y	Y	141L2AA/AT
	HP Z2 Tower Dust Filter and bezel	Y	Y	141L3AA/AT
	HP Z2 Internal Serial Port and PS/2 Port	Y	Y	141K9AA/AT
	HP PCIe x1 Parallel Port Card	Y	Y	N1M40AA
	HP DP Flex Port 2020	Υ	Υ	141J7AA/AT
	HP Dual USB-A 3.2 Gen1 Flex 2020	Υ	Υ	141J8AA/AT
	HP Front Type-C SuperSpeed USB 20Gbps port	Υ	Υ	201F4AA/AT
	HP HDMI Flex Port 2020	Υ	Υ	141K1AA/AT
	HP USB-C 3.2 Gen2 Alt Flex Port 2020	Y	Y	141K6AA/AT
	HP VGA Flex Port 2020	Y	Y	141K7AA/AT
	¹ Available in Q3, 2021	·	•	
Racking and Physical Security		Factory Configured	Option Kit	Option Kit Part Number
	HP Z2 Mini and Z2/Z4/Z6 TWR Depth Adjustable Fixed Rail Rack Kit	Υ	Υ	2A8Y5AA
Software		Factory Configured	Option Kit	Support Notes
	HP Performance Advisor	Υ	N	1
	HP PC Hardware Diagnostics UEFI (Windows OS only)	Υ	N	2
	HP PC Hardware Diagnostics Windows	Υ	N	
	HP Sure Sense	Υ	N	
	HP Notifications	Υ	N	
	HP Desktop Support Utility	Υ	N	



Supported Components

HP Documentation	Υ	N	
HP Image Assistant	N	N	
HP Support Assistant	N	N	
HP QuickDrop	Υ	N	
myHP	Υ	N	
Wolf Pro Security			3

Notes:

- 1. Supports, and preinstalled with Windows 10 and Windows 11 only. Also available as a free download from http://www.hp.com/go/performanceadvisor
- 2. Windows OS only
- 3. HP Wolf Pro Security Edition is available preloaded on select SKUs, and, depending on the HP product purchased, includes a license with a term length communicated to you at purchase and in your order confirmation email. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: 7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition is effective upon 4 months after the date the HP Product was shipped by HP and will continue for the term communicated to you at purchase and in your order confirmation email ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support. Notwithstanding the foregoing, the license shall expire no later than one year after the fixed term of the subject license ends.

Application Software

	Factory	Support	
	Configured	Option Kit	Notes
HP ZCentral Remote Boost	N	N	
Data Science Stack	Υ	N	1,2
WSL2/Ubuntu Data Science Stack	Υ	N	1,3
Wolf Pro Security			4

*Not all Application Software for Z Desktop Workstations is included with purchase.

Note 1: Only available with NVIDIA graphics cards selections.

Note 2: Only available with Ubuntu 20.04 LTS preinstall.

Note 3: Only available with Windows 10 Pro/Pro for Workstations or Windows 11 Pro/Pro for Workstations.

Note 4: HP Wolf Pro Security Edition is available preloaded on select SKUs, and, depending on the HP product purchased, includes a license with a term length communicated to you at purchase and in your order confirmation email. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: 7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition is effective upon 4 months after the date the HP Product was shipped by HP and will continue for the term communicated to you at purchase and in your order confirmation email ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support. Notwithstanding the foregoing, the license shall expire no later than one year after the fixed term of the subject license ends.



Supported Components

Operating Systems \

Windows 11 Pro²

Windows 11 Pro for Workstations²

Windows 11 Home - HP recommends Windows 11 Pro for business 2

Windows 10 Pro^{1,2}

Windows 10 Pro for Workstations^{1,2}

Windows 10 Home - HP recommends Windows 11 Pro for business 1,2

Linux®-readv

Ubuntu Linux 20.04 LTS

Red Hat® Enterprise Linux® (RHEL) Workstation — paper license (1yr) only (not preinstalled)

NOTE 1: Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

NOTE 2: Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

NOTE: Windows 11 Pro/Pro for Workstations and Windows 10 Pro/Pro for Workstations is available with Windows Subsystem for Linux® (WSL 2).

NOTE: For detailed OS/hardware information for Linux, see:

http://www.hp.com/support/linux_hardware_matrixNotes: For detailed OS/hardware information for Linux, see: http://www.hp.com/support/linux_hardware_matrix



Supported Components

HP BIOS

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate
 the HP Z2 G8 Workstation into the enterprise, such as PXE, remote recovery, remote
 configuration, remote control, and BIOS (F10) Setup support for 15 languages.
- Network firmware updates Update your BIOS via the cloud or standardize on a BIOS version hosted on an Enterprise network.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- UEFI specification version 2.7
- Absolute Persistence agent For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies so component temperatures are managed for high reliability and to assist in operating the HP Workstation computer in any enterprise environment.
- Acoustic performance Industry leading acoustic emissions across the range of operating conditions.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Workstation computers, including BIOS updates from within Windows (HP Firmware Update and Recovery), Capsule update, HP Client Manager, and fail-safe recovery. In addition, the HP BIOS Configuration Utility enables replication of BIOS settings within Windows while the Replicated Setup feature provides the same capability within BIOS (F10) Setup. The BIOS Configuration Utility is available from the HP support website.
- HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery

Additional HP BIOS Features:

- Power-On password Helps prevent an unauthorized user from powering on the system.
- Administrator password Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
- S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
 - -Power to expansion connectors / slots
 - -Most Wake events other than power buttons and WOL(Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled)
 - -USB charging ports

HP Sure Start Gen7 Start

- BIOS Integrity checking Sure Start protection ensures that only trusted BIOS code is executed
 and not rootkits, viruses and malware. Verification is done upon boot up, shutdown and while
 the system is on.
- Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is
 policy driven for better manageability. Start is set by default to automatically repair the BIOS if
 corrupted or compromised but is policy driven for better manageability.
- Protecting beyond BIOS Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.



Supported Components

 Audit enabled – System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating

NOTE: HP Sure Start Gen7 is available on HP Workstation products equipped with Intel® 11th generation processors.

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS
HP BIOSphere Gen6¹
BIOS Update via Network
HP Secure Erase²
Absolute Persistence Module³
Pre-boot Authentication
HP Wake on WLAN
HP DriveLock & Automatic DriveLock

Software

HP Support Assistant

HP Image Assistant

HP Desktop Support Utility

HP Documentation

HP Notifications

HP PC Hardware Diagnostics UEFI

HP PC Hardware Diagnostics Windows

HP Performance Advisor4

ZCentral Remote Boost⁵

My HP

HP QuickDrop

Manageability Features

HP Driver Packs⁶

HP System Software Manager (SSM)

HP BIOS Config Utility (BCU)

HP Manageability Integration Kit Gen47

HP Smart Support¹⁶

Client Security Software

HP Client Security Manager Gen78 including:

(including Credential Manager, HP Password Manager⁹, HP Spare Key)

HP Power On Authentication

Microsoft Defender¹⁰

Security Management

HP Sure Click¹¹

HP Sure Start Gen7¹²

HP Sure Run Gen4¹³

HP Sure Sense¹⁴

HP Sure Recover Gen4¹⁵

Wolf Pro Security9

[1] HP BIOSphere Features may vary depending on the platform and configurations.



Supported Components

[2] HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

[3] Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

[4] HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at:

https://www8.hp.com/us/en/workstations/performance-advisor.html

[5] HP ZCentral Remote Boost Sender does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase through 2022. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. ZCentral Remote Boost Sender for non-Z Hardware requires a license and Windows 10, RHEL/CentOS (7 or 8), or UBUNTU 18.04 or 20.04 LTS operating systems. macOS (10.14 or newer) operating system and ThinPro 7.2 are only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.

[6] HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

[7] HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html

[8] HP Client Security Manager Gen6 requires Windows and is available on the select HP Elite and Pro PCs.

[9] HP Wolf Pro Security Edition is available preloaded on select SKUs, and, depending on the HP product purchased, includes a license with a term length communicated to you at purchase and in your order confirmation email. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: 7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition is effective upon 4 months after the date the HP Product was shipped by HP and will continue for the term communicated to you at purchase and in your order confirmation email ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support. Notwithstanding the foregoing, the license shall expire no later than one year after the fixed term of the subject license ends.

[10] Microsoft Defender Opt in and internet connection required for updates.

[11] HP Sure Click requires Windows 10/11 Pro or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.

[12] HP Sure Start is available on select HP PCs and requires Windows 10 or Windows 11.

[13] HP Sure Run is available on HP Workstation products equipped with 8th generation Intel® or AMD® processors.

[14] HP Sure Sense requires Windows 10/11 Pro or Enterprise. See product specifications for availability.

[15] HP Sure Recover is available on select HP PCs and requires an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.

[16] HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.



System Technical Specifications

System Board

System Board Form

Customized PCB 14.197x9.895 inch

Factor

Processor Socket Single LGA-1200

CPU Bus Speed DMI

Chipset Intel® PCH W580

Super I/O Controller Nuvoton SIO18

Memory Expansion Slots 4 DDR4 memory slots

Memory Type Supported DDR4, UDIMM (Unbuffered), ECC& non-ECC

Memory Modes Non-Interleaved for single channel. Interleaved when both channels are populated.

Memory Speed Supported Up to 3200MT/s DDR4 **Memory Protection** ECC available on data

Maximum Memory 128GB¹

Memory Configuration (Supported)

4GB, 8GB, 16GB and 32GB non-ECC/8GB, 16GB and 32GB ECC unbuffered DIMMs are supported. ECC

and non-ECC memory DIMMs cannot be mixed in the same system

PCI Express Connectors (1) PCI Express Gen4 slot x16 mechanical/x16 electrical (full height, full length)

(1) PCI Express Gen3 slot x4 mechanical/x1 electrical (full height, full length, open-ended)

(1) PCI Express Gen3 slot x16 mechanical/ x4 electrical (full height, full length)

(1) PCI Express Gen3 slot x4 mechanical/ x4 electrical (full height, full length, open-ended)

(1) M.2 2280 Storage (PCIe Gen4 x4)² (1) M.2 2280 Storage (PCIe Gen3 x4)²

(1) M.2 2230 WLAN (PCIe Gen3 x1+ Intel CNVi) 2

NOTE: The PCIe Gen 4 x16 slot is meant for HP qualified cards, configured or after market. HP does not provide warranty support for 3rd party cards.

Supported Drive Interfaces SATA Integrated (4) Serial ATA interfaces (6Gb/s SATA).

RAID 0 and 1 supported. Factory integrated RAID for

Microsoft Windows only.

Integrated Graphics Intel® UHD Graphics 730 (on Core i5-11400 processors);

Intel® UHD Graphics 730 (on Core i5/i7/i9-11xxx processors);

Intel® UHD Graphics P750 for Xeon processors

Based on Unified Memory Architecture (UMA) - a region of system memory is reserved and dedicated to the graphics

display.

Support for Microsoft DirectX 12, OpenGL 4.6 and OpenCL 3.0

on Intel® UHD Graphics 730/750;

Based on Unified Memory Architecture (UMA) - a region of system memory is reserved and dedicated to the graphics

display.

Support for Microsoft DirectX 12, OpenGL 4.6 and OpenCL 3.0

on Intel® UHD Graphics P750;

3 DP 1.4 graphics ports integrated in motherboard; Supports

up to three simultaneous displays across

DisplayPort*/HDMI*/DVI outputs.

Max. resolution supported on onboard DP 1.4/HBR2 ports:

4096x2304 @ 60Hz,

24bpp

Max. resolution supported on flexIO DP 1.4/HBR3 ports:

5120x3200 @ 60Hz,

24bpp



System Technical Specifications

Network Controller Integrated Ethernet PHY Connection I219LM. Management

capabilities: WOL, PXE 2.1 and AMT 15

SerialYes- requires optional Serial Port Adapter Kit2nd SerialYes- requires optional Serial Port Adapter Kit

USB Connector(s) Front 2 Type-A SuperSpeed USB 5Gbps signaling rate port (1

charge port supports up to 5V/2.1A);

2 Type-A SuperSpeed USB 10Gbps signaling rate port; 1 Type-C® SuperSpeed USB 20Gbps signaling rate port

(optional, charge supports up to 5V/3A)

Rear 3 High-speed USB 480Mbps signaling rate port; 1 Type-A

SuperSpeed USB 5Gbps signaling rate port; 2 Type-A

SuperSpeed USB 10Gbps signaling rate port;

Flex I/O option:

1 Type-C[®] SuperSpeed USB 10Gbps signaling rate (Power Delivery 15W, Alt Mode DisplayPort); 1 Dual Type-A

SuperSpeed USB 5Gbps signaling rate

1 High-speed USB 480Mbps signaling rate port

HD Integrated Audio Realtek ALC3205

Flash ROM Yes
CPU Fan Header Yes
Memory Fan Header None

Chassis Fan Header 1 Rear System Chassis Fan Header, 1 Graphic chassis Fan Header.

Front PCI Fan Header None

Front Control

Panel/Speaker Header Yes

CMOS Battery Holder -

Lithium Yes

Integrated Trusted Integrated TPM 2.0 (Infineon SLB9670)

Internal

Platform Module Convertible to FIPS 140-2 Certified mode through firmware v7.85

The TPM module disabled where restricted by law, i.e. Russia.

Power Supply Headers Yes
Power Switch, Power LED
& Hard Drive LED Header Yes
Clear Password Jumper None

Keyboard/Mouse USB or PS/2 (option)

Power Supply 700W EPA92, 500W EPA90 and 350W EPA92

¹Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows® 10 Professional 64 bit, Red Hat Linux 64-bit. 32-bit Windows Operating Systems support up to 4 GB.

²M.2 storage supports compatible devices up to 80mm

System Technical Specifications

PCIe Hold-down / Blower Kit Specification

Please refer to section Supported Components - Graphics for supported cards list.

Performance Class	Product Name	Slots space Required	Max Card Count	Number of Cards Require PCIe Hold- down / Blower Kit
Ultra High-End 3D	NVIDIA® RTX® A5000 24GB	2	1	1
High-End 3D	NVIDIA® RTX® A4000 16GB	2	1	1
	AMD Radeon™ Pro W5700 8GB	2	1	1
	AMD Radeon™ Pro W5500 8GB	1	1	1
Mid-range 3D	NVIDIA® T1000 4GB	1	2	2
	AMD Radeon™ Pro WX 3200 4GB	1	2	2
Entry	NVIDIA® Quadro® P400 2GB	1	2	3

NOTE: The PCIe Hold-down / Blower Kit is automatically included when the 700W chassis is configured.

System Configuratio	ns							
Example Configuration	Processor Info	Intel Core i5-	- 11400 2.60	GHz 6C65W				
#1	Memory Info	8GB (1x 8GB	8GB (1x 8GB) 3200 MHz DDR4 non-ECC					
	Graphics Info	Intel® UHD Integrated Graphics 730						
	Disks/Optical/Floppy	1x SATA 1TB 7.2k rpm / 1x 9.5mm Slim ODD						
	PSU	350W						
	Other							
Energy Consumption		115 VAC 230 VAC 100				VAC		
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows long Idle (S0)	18.	.98	19.287		19.175		
	Windows short Idle (S0)	20.	713	21.	005	20.	20.917	
	Windows Busy Typ (S0)	95.	045	96	.66	96.	118	
	Windows Busy Max (S0)	94.	409	93.	629	93.	654	
	Sleep (S3)	0.887	0.83	0.968	0.853	0.963	0.923	
	Off (S5)	0.645	0.604	0.674	0.567	0.655	0.615	
	Zero Power Mode (EuP)	0.2	238	0.2	98	0.199		

Heat Dissipation

(Btu/hr)

LAN

Enabled

Windows Idle (S0)

Windows short Idle (S0)

115 VAC

64.75976

70.672756

LAN

Disabled

230 VAC

65.807244

71.66906

LAN

Disabled

LAN

Enabled

LAN

Disabled

100 VAC

65.4251

71.368804

LAN

Enabled

System Technical Specifications

	Windows Busy Typ (S0)	324.2	9354	329.8	80392	327.9	54616	
	Windows Busy Max (S0)	322.1	23508	319.40	62148	319.547448		
	Sleep (S3)	3.026444	2.83196	3.302816	2.910436	3.285756	3.149276	
	Off (S5)	2.20074	2.060848	2.299688	1.934604	2.23486	2.09838	
	Zero Power Mode (EuP)	0.81	2056	1.01	6776	0.67	8988	
Example Configuration	Processor Info	Intel Core i7-	- 11700 2.50	GHz 8C65W				
#2	Memory Info	16GB (2x 8G	16GB (2x 8GB) 3200MHz DDR4 non-ECC					
	Graphics Info	NVIDIA Quad	ro T1000 4 G	iB				
	Disks/Optical/Floppy	1x SATA 256	1x SATA 256GB SSD / 1x 9.5mm Slim ODD					
	PSU	500W						
	Other							
Energy Consumption		115	VAC	230 VAC		100 VAC		
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows long Idle (S0)	23.	.49	23.922		23.695		
	Windows short Idle (S0)	25.	186	25.	205	24.	933	
	Windows Busy Typ (S0)	137.	.849	138	3.76	134	.09	
	Windows Busy Max (S0)	128	.184	129).18	125	5.28	
	Sleep (S3)	0.994	0.95	0.963	0.853	0.878	0.824	
	Off (S5)	0.737	0.706	0.646	0.572	0.74	0.703	
	Zero Power Mode (EuP)	0.2	:18	0.2	:99	0.223		

Heat Dissipation		115	VAC	230	VAC	100 VAC		
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	80.1	4788	81.62	1864	80.84734		
	Windows short Idle (S0)	85.93	4632	85.99946		85.071396		
	Windows Busy Typ (S0)	470.3	40788	473.4	4912	457.5	457.51508	
	Windows Busy Max (S0)	437.3	63808	440.7	'6216	427.4	5536	
	Sleep (S3)	3.391528	3.2414	3.285756	2.910436	2.995736	2.811488	
	Off (S5)	2.514644	2.408872	2.204152	1.951664	2.52488	2.398636	
	Zero Power Mode (EuP)	0.743816 1.020188		0.760876				
xample Configuration	Processor Info	Intel Core i9- 11900K 3.50GHz 8C125W						
#3	Memory Info	64GB (2x 32GB) 3200 MHz DDR4 ECC						
	Graphics Info	NVIDIA GeFo	rce RTX 3070) 8 GB				
	Disks/Optical/Floppy	1x SATA 512	GB SSD					
	PSU	700W						
	Other							
Energy Consumption		115	VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows long Idle (S0)	26	5.2	26.	301	26.	251	
	Windows short Idle (S0)	27.	866	28.087		27.588		



System Technical Specifications

Zero Power Mode (EuP)	0.599 0.553 0.215		0.031		0.303	
Off (S5)	0.500	0.553	0.651	0.524	0.565	0.507
Sleep (S3)	1.009	0.973	1.025	0.862	0.951	0.913
Windows Busy Max (S0)	199.344		200.99		198.541	
Windows Busy Typ (S0)	232.415		232.99		230.363	

Heat Dissipation		115	VAC	230 VAC		100 VAC		
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	89.3	944	89.73	9012	89.56	89.568412	
	Windows short Idle (S0)	95.07	'8792	95.83	2844	94.130256		
	Windows Busy Typ (S0)	792.9	9998	794.9	6188	785.9	98556	
	Windows Busy Max (S0)	680.1	61728	685.7	7788	677.4	21892	
	Sleep (S3)	3.442708	3.319876	3.4973	2.941144	3.244812	3.115156	
	Off (S5)	2.043788	1.886836	2.221212	1.787888	1.92778	1.729884	
	Zero Power Mode (EuP)	0.73358		1.003128		0.774524		

Example Configuration	Processor Info	Intel Xeon W- 1370P 3.60G 8C125W
#4	Memory Info	128GB (4x 32GB) 3200 MHz DDR4 ECC
	Graphics Info	NVIDIA Quadro RTX A4000 16 GB
	Disks/Optical/Floppy	1x SATA 1TB SSD Z Turbo
	PSU	700W
	Other	

Energy Consumption		115	VAC	230	VAC	100	VAC
(Watts)		LAN Enabled	LAN Enabled LAN Disabled		LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	TE	3D	TBD		TBD	
	Windows short Idle (S0)	TBD		TBD		TBD	
	Windows Busy Typ (S0)	TBD TBD		3D	TBD		
	Windows Busy Max (S0)	TE	3D	TE	3D	TE	3D
	Sleep (S3)	TBD	TBD	TBD	TBD	TBD	TBD
	Off (S5)	TBD	TBD	TBD	TBD	TBD	TBD
	Zero Power Mode (EuP)	TBD		TBD		TBD	

Heat Dissipation		115	VAC	230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	TE	3D	TBD		TBD	
-	Windows short Idle (S0)	TBD		TBD		TBD	
	Windows Busy Typ (S0)	TBD		TBD		TBD	
	Windows Busy Max (S0)	TE	3D	TE	3D	TE	BD
	Sleep (S3)	TBD	TBD	TBD	TBD	TBD	TBD
	Off (S5)	TBD	TBD	TBD	TBD	TBD	TBD
	Zero Power Mode (EuP)	TBD		TBD		TBD	

System Technical Specifications

Example Configuration	Processor Info	Intel Xeon W- 1350 3.30GHz 6C80W
#5	Memory Info	16GB (2x 8GB) 3200 MHz DDR4 ECC
1	Graphics Info	NVIDIA Quadro RTX A5000 24 GB
1	Disks/Optical/Floppy	1x SATA 1TB SSD Z Turbo
1	PSU	700W
	Other	

Energy Consumption		115	VAC	230	VAC	100 VAC	
(Watts)		LAN Enabled LAN Disabled		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	TE	3D	TBD		TBD	
	Windows short Idle (S0)	TBD		TBD		TBD	
	Windows Busy Typ (S0)	TBD		TBD		TBD	
	Windows Busy Max (S0)	TE	3D	TE	3D	TE	BD
	Sleep (S3)	TBD	TBD	TBD	TBD	TBD	TBD
	Off (S5)	TBD	TBD	TBD	TBD	TBD	TBD
	Zero Power Mode (EuP)	TBD		TBD		TBD	

Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	TBD		TBD		TBD	
1	Windows short Idle (S0)	TBD		TBD		TBD	
1	Windows Busy Typ (S0)	TBD		TBD		TBD	
	Windows Busy Max (S0)	TBD		TBD		TBD	
	Sleep (S3)	TBD	TBD	TBD	TBD	TBD	TBD
	Off (S5)	TBD TBD		TBD	TBD	TBD	TBD
	Zero Power Mode (EuP)	TBD		TBD		TBD	

NOTE: The Power Supply Efficiency report may be found at the following links:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2



System Technical Specifications

Operating Voltage Range 90-269 VAC **Rated Voltage Range** 100-240 VAC **Rated Line Frequency** 50-60 Hz **Operating Line Frequency** 47-66 Hz

Range

Rated Input Current 6A @ 100-240V

Heat Dissipation Typical: 444 btu/hr (112 kcal/hr) Maximum: 1484 btu/hr (374 kcal/hr)

Yes

Yes

ENERGY STAR® certified

(Config Dependent)

CECP Compliant @ 220V Yes

FEMP Standby Power

Compliant

Built-in Self Test (BIST)

LED

Surge Tolerant Full Ranging Power Supply (withstands power surges

up to 2000V)

Hood Lock Header Yes ErP Lot 6- Tier 1 Yes Compliance @ 230V (<1W

in S5 - Power Off)

ErP Lot 6- Tier 2 Yes

Compliance @ 230V (<0.5W in S5 - Power Off)

Declared Noise Emissions	(Entry-level, Mid-level, a	nd High-end configurations; tested on floo	or)				
System Configuration	Processor Info	Intel® Core™ i9-11900 2.5 GHz 8C CPU					
(Entry level)	Memory Info	128GB DDR4-3200 nECC (4x32GB) RAM					
	Graphics Info	Intel® UHD	Intel® UHD				
	Disks/Optical	1 TB SATA 6Gb/s SSD / No Optical /					
	Power Supply	700W PSU					
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)				
	Idle	3.31	13.8				
	Hard drive Operating (random reads)	3.4	15.7				
System Configuration	Processor Info	Intel® Xeon® processor W-1290 3.2 GHz 10C CPU					
(Mid-level)	Memory Info	128GB DDR4-2933 ECC (4x32GB) RAM					
	Graphics Info	NVIDIA® Quadro® RTX 5000 16GB					
	Disks/Optical	2 x 2TB SATA 7200 rpm 6Gb/s / No Optical					
	Power Supply	700W PSU					
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)				
	Idle	3.55	18.4				

Yes, with Wake-on-LAN disabled: <1W in S4/S5 - Power Off

System Technical Specifications

Hard drive Operating (random reads)	3.9	22.4			
Processor Info	Intel® CoreTM i9-11900K 3.5GHz 8C CPU				
Memory Info	128GB DDR4-2933 nECC (4x32GB) RAM				
Graphics Info	NVIDIA® Quadro® RTX 5000 16GB				
Disks/Optical	2 x 2TB SATA 7200 rpm 6Gb/s / No Optical				
Power Supply	700W PSU				
	Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)			
Idle	3.64	18.8			
Hard drive Operating (random reads)	3.85	20.8			
((random reads) Processor Info Memory Info Graphics Info Disks/Optical Power Supply Idle Hard drive Operating	Arandom reads) Processor Info Intel® CoreTM i9-11900K 3.5GHz 8C CP Memory Info 128GB DDR4-2933 nECC (4x32GB) RAM Graphics Info NVIDIA® Quadro® RTX 5000 16GB 2 x 2TB SATA 7200 rpm 6Gb/s / No Op Power Supply Sound Power (LWAd, bels) Idle 3.64 Hard drive Operating 3.85			

Environmental Requirements

Temperature Operating: 5° to 35° C (40° to 95° F)

Non-operating: -40° to 60° C (-40° to 140° F)

Maximum rate of change: 10°C/hr

Humidity Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

Maximum Altitude Operating (with Rotational Hard Drives): 3,048 m (10,000 feet)

Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Cooling for details.

Dynamic Shock

Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g)

square: 422 cm/s, 20q

Vibration

Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g²/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz

Cooling Above 1524 m (5,000 feet) altitude, the maximum operating temperature

is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation,

up to 3048 m (10,000 feet)

Physical Security and Serviceability

Access Panel Tool-less

Includes system board and memory information

Optical Drive Tool-less, except for Screw-In carrier

Hard Drives Tool-less, except for 2.5" bay

Expansion Cards Tool-less

Processor Socket Tool-less, except for the processor heatsink **Blue User Touch Points** Yes, on tool-less internal chassis mechanisms

Color-coordinated Cables Yes

and Connectors

MemoryTool-lessSystem BoardScrew-In



System Technical Specifications

Padlock Support Yes (optional): Locks side cover and secures chassis from theft

0.22-in diameter padlock loop at rear of system

Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft **Cable Lock Support**

3 mm x 7 mm slot at rear of system

Threaded feature at rear of system

Universal Chassis Clamp

Lock Support

Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows

multiple units to be chained together when used with optional cable

Solenoid Lock and Hood

Sensor

Yes (optional)

Nο

The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through

software and a password. You can also lock and unlock the chassis remotely over the network. The

Sensor Kit detects when the access panel has been removed.

Rear Port Control Cover

CPUs and Heatsinks A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be

removed. CPU removal is tool-less

Internal Speaker

70mm x 70mm x 25mm 4-wire PWM (non-serviceable) **Power Supply Fans**

Access Panel Key Lock

Integrated Chassis

Power Supply

Rear Recessed Handle

Handles

Requires T15 Torx or flat blade screwdriver

PCI Card Retention Yes, rear (all), middle (optional), front (full-length cards with extender)

Service, Support, and Warranty

On-site Warranty and Service¹: Three-years, limited warranty and service offering delivers on-site, next business-day² service for parts and labor and includes free telephone support³ 8am - 5pm. Global coverage² ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering, 24/7 operation will not void the HP warranty.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider. and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at:

http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

BIOS

BIOS 64-bit Services BIOS supports 64-bit Operating systems only.

PCI 3.0 Support Full BIOS support for PCI Express through industry standard interfaces.

ATAPI ATAPI Removable Media Device BIOS Specification Version 1.0.

BBS BIOS Boot Specification v1.01.

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows, WMI is WMI Support

fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Boot Spec 1.01+

Provides more control over how and from what devices the workstation will boot.

BIOS Power On Users can define a specific date and time for the system to power on.



System Technical Specifications

ROM Based Computer

Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM Flash Recovery with

Video

Recovers system BIOS in corrupted Flash ROM.

Replicated Setup

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt).

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup).

SMBIOS Boot Control System Management BIOS 3.2. for system management information. Disables the ability to boot from removable media on supported devices.

Memory Change Alert Thermal Alert

Alerts management console if memory is removed or changed. Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

• ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash **ACPI (Advanced**

Provides secure, fail-safe ROM image management from a central network console.

Allows the system to enter and resume from low power modes (sleep states).

Configuration and Power Management Interface)

Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 6.0 for full compatibility with 64-bit operating systems.

Ownership Tag

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Remote Wakeup/Remote

Shutdown

System administrators can power on, restart, and power off a client computer from a remote location.

Instantly Available PC (Suspend to RAM - ACPI

sleep state S3)

Remote System Installation via F12 (PXE

2.1) (Remote Boot from

Server)

Allows for very low power consumption with quick resume time.

Allows a new or existing system to boot over the network and download software, including the operating system.

ROM revision levels

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW applications can use and report this information.

System board revision level

Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified.

Start-up Diagnostics (Power-on Self-Test) Auto Setup when new hardware installed

Assesses system health at boot time with selectable levels of testing.

System automatically detects addition of new hardware.

Keyboard-less Operation The system can be booted without a keyboard.

Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with **Localized ROM Setup**

local keyboard mappings.

The user or MIS to set a unique tag string in non-volatile memory. Asset Tag

Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification

Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics.

(Pre-video) critical errors are reported via beeps and blinks on the power LED.

Revision 2.7

ACPI Advanced Configuration and Power Management Interface, Version 6.0



System Technical Specifications

ATA (IDE) AT Attachment 6 with Packet Interface (ATA/ATAPI-6). Revision 3b **CD Boot** "El Torito" Bootable CD-ROM Format Specification Version 1.0

EDD Enhanced Disk Drive Specification Version 1.1

BIOS Enhanced Disk Drive Specification Version 3.0

EHCI Enhanced Host Controller Interface for Universal Serial Bus. Revision 1.0

PCI PCI Local Bus Specification, Revision 2.3

> PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7

PCI Express PCI Express Base Specification, Revision 2.0

PCI Express Base Specification, Revision 3.0 PCI Express Base Specification, Revision 4.0

PMM POST Memory Manager Specification, Version 1.01

SATA Serial ATA Specification, Revision 1.0a

> Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B

Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9670). **TPM**

Common Criteria EAL4+ certified.

FIPS 140-2 Certification

TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

UHCI Universal Host Controller Interface Design Guide, Revision 1.1

USB Universal Serial Bus Revision 1.1 Specification

Universal Serial Bus Revision 2.0 Specification

Universal Serial Bus Revision 3.1 Specification

SMBIOS System Management BIOS Reference Specification, Version 3.2

External BIOS simulator found at: http://csrsml.itcs.hp.com/

Social and Environmental Responsibility

& Declarations

Eco-Label Certifications This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- **US ENERGY STAR®**
- US Federal Energy Management Program (FEMP)
- EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO Certified configurations available*
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*



System Technical Specifications

*TCO Certified configurations available when ENERGY STAR configurations are selected with a USB Type-C® connector. ENERGY STAR available with a combination of high-performance CPU's, high-performance GPU's and select memory configurations.

Sustainable Impact Specifications

- 45% post-consumer recycled plastic
- External Power Supply 90% Efficiency
- Low halogen
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy Consumption (in accordance with US ENERGY STAR® test

method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Sort idle)	40.30 W	40.88 W	38.25 W
Normal Operation (Long idle)	38.70 W	38.89 W	38.7 W
Sleep	2.56 W	2.77 W	2.75 W
Off	0.81 W	0.81 W	0.81 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	140 BTU/hr	140 BTU/hr	140 BTU/hr
Normal Operation (Long idle)	132 BTU/hr	135 BTU/hr	132 BTU/hr
Sleep	9 BTU/hr	9 BTU/hr	9 BTU/hr
Off	3 BTU/hr	3 BTU/hr	3 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

System Technical Specifications

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and IS01043.
- This product is 94.2% recycle-able when properly disposed of at end of life.

Packaging Materials

PAPER/Corrugated **External:** 1158 q Internal: PAPER/Molded pulp 390 q PLASTIC/Polyethylene low 28 q

density

The plastic packaging material contains at least 80% recycled content.

The corrugated paper packaging materials contains at least 100% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/qlobalcitizenship/environment/supplychain/gen specifications.html):

- **Asbestos**
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- **Chlorinated Hydrocarbons**
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds



System Technical Specifications

- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

footnotes

- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.



System Technical Specifications

- Fiber cushions made from 100% recycled wood fiber and organic materials.
- Plastic cushions are made from >90% recycled plastic.



Technical Specifications - Processors

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	Hyper- Threading	Integrated Graphics	Intel® Turbo Boost Technology³	Featuring Intel® vPro® Technology ⁴	16GB Intel® Optane™ memory²	TDP (W)
Intel® Core™ i9 11900K Processor	8	3.5	16	3200	TRUE	Intel® UHD Graphics 750	5.2	TRUE	Υ	125
Intel® Core™ i9 11900F Processor	8	2.5	16	3200	TRUE	N/A	5.2	N/A	Υ	65
Intel® Core™ i9 11900 Processor	8	2.5	16	3200	TRUE	Intel® UHD Graphics 750	5.2	TRUE	Υ	65
Intel® Core™ i7 11700K Processor	8	3.6	16	3200	TRUE	Intel® UHD Graphics 750	5	TRUE	Υ	125
Intel® Core™ i7 11700 processor	8	2.5	16	3200	TRUE	Intel® UHD Graphics 750	4.9	TRUE	Υ	65
Intel® Core™ i5 11600K processor	6	3.9	12	3200	TRUE	Intel® UHD Graphics 750	4.9	TRUE	Υ	125
Intel® Core™ i5 11600 processor	6	2.8	12	3200	TRUE	Intel® UHD Graphics 750	4.8	TRUE	Υ	65
Intel® Core™ i5 11500 processor	6	2.7	12	3200	TRUE	Intel® UHD Graphics 750	4.6	TRUE	Υ	65
Intel® Core™ i5 11400F processor	6	2.6	12	3200	TRUE	N/A	4.4	N/A	Υ	65
Intel® Core™ i5 11400 processor	6	2.6	12	3200	TRUE	Intel® UHD Graphics 730	4.4	N/A	Υ	65
Intel® Xeon® W- 1390P processor	8	3.5	16	3200	TRUE	Intel® UHD Graphics	5.2	TRUE	Υ	125
Intel® Xeon® W- 1390 processor	8	2.8	16	3200	TRUE	Intel® UHD Graphics	5.1	TRUE	Υ	80
Intel® Xeon® W- 1370P processor	8	3.6	16	3200	TRUE	Intel® UHD Graphics	5.2	TRUE	Υ	125
Intel® Xeon® W- 1370 processor	8	2.9	16	3200	TRUE	Intel® UHD Graphics	5.1	TRUE	Υ	80
Intel® Xeon® W- 1350P processor	6	4	12	3200	TRUE	Intel® UHD Graphics	5.1	TRUE	Υ	125
Intel® Xeon® W- 1350 processor	6	3.3	12	3200	TRUE	Intel® UHD Graphics	5	TRUE	Υ	80

^{1.} Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

^{2.} Intel® Optane™ memory is sold separately. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Available for HP commercial desktops and notebooks and for select HP workstations (HP Z240 Tower/SFF, Z2 Mini, ZBook Studio, 15 and 17 G5) and requires a SATA HDD, 7th Gen or higher Intel® Core™ processor or Intel® Xeon® processor E3-1200 V6 product family or higher, BIOS version with Intel® Optane™ supported, Windows 10 version 1703 or higher, M.2 type 2280-S1-B-M connector on a PCH Remapped PCIe Controller and Lanes in a x2 or x4 configuration with B-M keys that meet NVMeTM Spec 1.1, and an Intel® Rapid Storage Technology (Intel® RST) 15.5 driver.



Technical Specifications - Processors

- 3. The specifications shown in the Intel® Turbo Boost Technology column represent the maximum turbo frequency with one core active. Turbo boost stepping occurs in 100MHz increments. Processors that do not have turbo functionality are denoted as N/A. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information
- 4. For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See http://intel.com/vpro



Technical Specifications - Hard Drives

SATA Hard Drives for HP Workstations

500GB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity500GBProtocolSATAForm Factor3.5"ControllerAHCI

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm

Up to 600MB/s *

Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer

32MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average2 ms *Full Stroke21 ms *

Rotational Speed 7,200 rpm Logical Blocks 976,773,168

Operating Temperature 41° to 131° F (5° to 55° C)

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity 1TB
Protocol SATA
Form Factor 3.5"
Controller AHCI

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600 MB/s *

Buffer 64MB

Seek Time (typical reads, includes controller overhead, including settling)

Single Track 2 ms *

Average 11 ms *

Full Stroke 21 ms *

Rotational Speed 7,200 rpm Logical Blocks 1.953.525.168

Operating Temperature 41° to 131° F (5° to 55° C)

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2TB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity 2TB
Protocol SATA
Form Factor 3.5"

Technical Specifications - Hard Drives

Controller AHCI

Annualized Failure Rate

(based on Rated POH) <0.62% Height 1 in: 2.54 cm

Width **Media Diameter** 3.5 in: 8.9 cm

Up to 600MB/s *

Physical Size 4 in: 10.17 cm

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads, **Single Track** 2.0 ms * includes controller Average 11 ms * overhead, including 21 ms * **Full Stroke** settling)

Rotational Speed 7,200 rpm **Logical Blocks** 3,907,029,168

Operating Temperature 41° to 131° F (5° to 55° C)

*Actual performance may vary.

NOTE: For hard drives and solid state drives. GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity 1TB

Height 1 in; 2.54 cm **Protocol** SATA **Form Factor** 3.5" Controller AHCI Reliability 2.0M hours 8760/yr **Rated Power On Hours**

Annualized Failure Rate

(based on Rated POH) <0.62%

Width **Media Diameter** 3.5 in; 8.9 cm

Up to 600MB/s *

Physical Size 4 in: 10.17 cm

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer

Rate (Maximum)

128MB

Buffer

Seek Time (typical reads, **Single Track** 0.32ms* includes controller Average 7.45ms* overhead, including **Full Stroke** 14.2ms*

settling)

Rotational Speed 7.200 rpm

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s*

> **Sequential Write** up to 226MB/s*

Enterprise Class Features High Reliability



^{*}Actual performance may vary.

Technical Specifications - Hard Drives

NOTE: For hard drives and solid state drives, GB = 1 billion bytes, TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

2TB Capacity SATA **Protocol Form Factor** 3.5" **Controller** AHCI Reliability (MTBF) 2.0M hours 8760/yr **Rated Power On Hours Annualized Failure Rate** < 0.62%

(based on Rated POH) Rated for 24/7/365

Operation

Physical Size (Height) 1 in; 2.54 cm Physical Size (Width) 4 in; 10.17 cm **Media Diameter** 3.5 in: 8.9 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s*

Buffer 128MB

Seek Time (typical reads, **Single Track** 0.7ms* includes controller Average 8.5ms* overhead, including **Full Stroke** 15.7ms*

settling)

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s* Sequential Write up to 226MB/s*

Enterprise Class Features High Reliability

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity 4TB **Protocol** SATA **Form Factor** 3.5" Controller AHCI Reliability 2.0M hours **Rated Power On Hours** 8760/yr **Annualized Failure Rate** < 0.62%

(based on Rated POH)

Rated for 24/7/365

Operation

Physical Size (Height) 1 in; 2.54 cm Physical Size (Width) 4 in; 10.17 cm 3.5 in; 8.9 cm **Media Diameter**



Technical Specifications - Hard Drives

Physical Size 4 in; 10.17 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s*

Rate (Maximum)

Buffer 256MB

Seek Time (typical reads,
includes controller
overhead, includingSingle Track
Average0.7ms*8.5ms*Full Stroke15.7ms*

settling)

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s*

Sequential Write up to 226MB/s*

Enterprise Class High Reliability

Features

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity 8TB
Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability 2.0M hours

Width Media Diameter 3.5 in; 8.9 cm

Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s [1]

Rate (Maximum)

Buffer 256MB

Seek Time (typical reads,
includes controller
overhead, includingSingle Track
Average0.7ms*8.5ms*Full Stroke15.7ms*

settling)

Rotational Speed 7,200 rpm

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s¹

Sequential Write up to 226MB/s¹

Enterprise Class Features High Reliability

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500GB SATA 7.2K SED 2.5" HDD

Capacity 500GB
Protocol SATA
Form Factor 2.5"

Height 0.275 in; 0.7 cm

25ms (Typical)*

Technical Specifications - Hard Drives

Width Media Diameter 2.5 in; 6.36 cm

Physical Size 2.75 in; 6.99 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s*

Buffer 64MB

Seek Time (typical reads,
includes controllerSingle Track1ms*Average4.2ms*

overhead, including settling)

Full Stroke

Rotational Speed 7,200 rpm

Operating Temperature 32° to 131° F (0° to 60° C)

Self-Encrypting Drive Yes

Support

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP Z Turbo Drv PCIE-4X4 256GB TLC PCIe SSD (Z2G8)

Capacity 256GB Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 75TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 5500MB/s*

Sequential Write 2300MB/s*
Random Read 400K IOPS*
Random Write 400K IOPS*

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP Z Turbo Drv PCIE-4X4 Capacity 512GB TLC PCIe SSD Protocol

(Z2G8)

Capacity 512GB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 150TBW (TB Written)

Reliability (MTBF) 1.5M hours

InterfacePCI Express 4.0 x4 electricalOperating Temperature32° to 178° F (0° to 81° C)

Performance Sequential Read 6400MB/s*

Sequential Write 3400MB/s*

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Random Read 600K IOPS* 600K IOPS*

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP Z Turbo Drv PCIE-4X4 Capacity 1TB TLC PCIe SSD (Z2G8) Protocol

Capacity 1TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 800K IOPS*
Random Write 800K IOPS*

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP Z Turbo Drv PCIE-4X4 2TB TLC PCIe SSD (Z2G8)

Capacity 2TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 600TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write5000MB/s*Random Read800K IOPS*Random Write800K IOPS*

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP Z Turbo Drv 256GB TLC PCIe SED OPAL2 (Z2G8)

Capacity 256GB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe

^{*}Actual performance may vary.

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

NAND Type 3D TLC

Endurance 75TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 5500MB/s*

Sequential Write 2300MB/s*
Random Read 400K IOPS*
Random Write 400K IOPS*

Self-Encrypting Drive OPAL2

Support

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP Z Turbo Drv 512GB TLC PCIe SED OPAL2 (Z2G8) Capacity 512GB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

ControllerNVMeNAND Type3D TLC

Endurance 150TBW (TB Written)

Reliability 1.5M Hours

InterfacePCI Express 4.0 x4 electricalOperating Temperature32° to 178° F (0° to 81° C)

Performance Sequential Read 6400MB/s*

Sequential Write 3400MB/s*
Random Read 600K IOPS*
Random Write 600K IOPS*

Self-Encrypting Drive OPAL2

Support

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP Z Turbo Drv 1TB TLC PCIe SED OPAL2 (Z2G8) Capacity 1TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*

Technical Specifications - Hard Drives

Random Read 800K IOPS* **Random Write** 800K IOPS*

Self-Encrypting Drive

OPAL2

Support

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP Z Turbo Drv 2TB TLC PCIe SED OPAL2 (Z2G8) Capacity 2TB Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 600TBW (TB Written)

Reliability 1.5M Hours

InterfacePCI Express 4.0 x4 electricalOperating Temperature32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 800K IOPS*
Random Write 800K IOPS*

OPAL2

Self-Encrypting Drive 0

Support

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIE TLC Capacity SSD (Z2G8) Protocol

Capacity 256GB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 200TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 3.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3100MB/s*

Sequential Write 1400MB/s*
Random Read 200K IOPS*
Random Write 400K IOPS*

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Capacity 512GB



^{*}Actual performance may vary.

Technical Specifications - Hard Drives

512GB M.2 2280 PCIE TLC Protocol PCIe

SSD (Z2G8)

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 3.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3400MB/s*

Sequential Write 2500MB/s*
Random Read 380K IOPS*
Random Write 430K IOPS*

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB M.2 2280 PCIE TLC SSD (Z2G8)

Capacity 1TB
Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read 3400MB/s*

Sequential Write 2500MB/s*
Random Read 500K IOPS*
Random Write 440K IOPS*

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2TB M.2 2280 PCIE TLC SSD (Z2G8)

Capacity 2TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 600TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 3.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3400MB/s*

Sequential Write 2500MB/s*

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Random Read 430K IOPS* Random Write 500K IOPS*

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Technical Specifications - Graphics

Integrated Intel® UHD Graphics (Z2 G8) Form Factor Integrated in select Intel® Xeon®, Intel® Core™ i9/i7, and Intel® Core™ i5

processors.

Check specific platform specifications for selections.

Graphics Controller

Memory

Intel® UHD Graphics

Unified Memory Architecture (UMA) frame buffer. Graphics memory is

shared with system memory. Size selectable between 64 MB to 1024 MB via BIOS setting. Default size is 64 MB. Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (Intel® DVMT 5.0), to provide an optimal balance between graphics and system

memory use.

Connectors Check system platform specifications where Intel® UHD Graphics are

available.

Maximum Resolution Display Port: 4096 x 2160 (5120x3200 could be achieved if output from

FlexIO ports - DP/USB-C/TBT)

HDMI: 4096 x 2160 DVI: 1920x1200 VGA: 2048x1536

NOTE: For HDMI, DVI and VGA outputs, separate adapters may be required.

Shading Architecture

Supported Graphics APIs

Shader Model 6 compiler support

OpenGL 4.6 DirectX 12

Available Graphics

Drivers

Windows 10

NVIDIA® Quadro® P400 2GB Graphics Form Factor Single Slot, Low Profile (2.713" H x 5.7" L)

Graphics Controller NVIDIA® Quadro® P400 Graphics Card

Max Power: 30 Watts

Cooling Solution: Active fan heatsink

Bus TypePCI Express 3.0 x16MemorySize: 2 GB GDDR5Maximum ResolutionDisplayPort™ 1.4:

- up to 3x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)

Display Output 3 mDP (Mini DisplayPort™) 1.4 Connectors **Shading Architecture** Full Microsoft DirectX 12 Shader Model 5.1

Supported Graphics APIs Open

OpenGL 4.5 DirectX 12

DirectX 12 Vulkan 1.0

API support includes: CUDA, OpenCL 1.x

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html



Technical Specifications - Graphics

Notes *P400 only have mini-DisplayPort™ (mDP) video ports.

Note: AMO kits for P400 Adapters

- Two mDP-to-DP Adapters are included in the P400 AMO kits.
- If more mDP-to-DP Adapters are needed, Adapters can be ordered separately:
 - 2MY05AA HP Single miniDP-to-DP Adapter Cable

NVIDIA® T400 2GB Graphics Form Factor Dimensions: 2.713" H x 6.137" L

Single Slot, Low Profile

Weight: 124g

Graphics Controller NVIDIA® T400 Graphics Card

GPU: 384 CUDA cores Power: 30 Watts Cooling: Active

Bus TypePCI Express 3.0 x16MemorySize: 2 GB GDDR6

Memory Interface: 64-bit Memory Bandwidth: 80 GB/s

Connectors 3x mDP

Maximum Resolution 3x 5120 x 2880 x 24 bpp @ 60Hz

Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulkan 1.0

API support includes: CUDA, OpenCL 1.x

Available Graphics

Drivers

Windows 11 Windows 10

Linux

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T600 4GB Graphics **Form Factor** Dimensions: 2.713" H x 5.7" L

Single Slot, Low Profile

Graphics Controller NVIDIA® T600 Graphics Card

GPU: 640 CUDA cores Power: 40 Watts Cooling: Active

Bus TypePCI Express 3.0 x16MemorySize: 4 GB GDDR6

Memory Interface: 128-bit Memory Bandwidth: 160 GB/s

Connectors 4x mDP

Maximum Resolution 7680 x 432- @ 60Hz



Technical Specifications - Graphics

Display Output Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulkan 1.0

4x mDP

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL

Available Graphics

Drivers

Windows 11 Windows 10 Linux

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

AMD Radeon™ Pro WX 3200 4GB Graphics

Form Factor

Low-Profile Single Slot (2.75 "H x 6.6" L)

Graphics Controller

Radeon™ Pro WX 3200 Power: 56 Watts

Cooling Solution: Active fan heatsink

Memory

4GB GDDR5 memory

Maximum Resolution

DisplayPort™ 1.4: - up to 4x 4096 x 2160 x 24 bpp @ 60Hz

Shading Architecture

Display Outputs

- supports Multi-Stream Transport (MST) Full Microsoft DirectX 12 Shader Model 5.1 4 mDP (Mini DisplayPort™) 1.4 Connectors

Supported Graphics APIs

DirectX® 12 OpenGL® 4.6 OpenCL™ 2.0 Vulkan™ 1.0

Available Graphics

Drivers

Windows 11 Windows 10

(Windows 7 64-bit available from AMD)

Linux[®] 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

- 1. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
- WX 3200 only has mini-DisplayPort™ (mDP) video ports. Two mDP-to-DP Adapters are included in the WX 3200 AMO kit. If more mDP-to-DP Adapters are needed, Adapters can be ordered separately:

2MY05AA

HP Single miniDP-to-DP Adapter Cable

NVIDIA® RTX A4000 16GB Form Factor **Graphics**

Full-Height Single Slot (4.4" Height x 9.5" Length)



Technical Specifications - Graphics

Graphics Controller NVIDIA® RTX A4000 Graphics

GPU: 6144 NVIDIA® CUDA® Parallel Processing Cores

Power: 140 Watts Cooling: Active

Memory 16GB GDDR6 memory

Memory Bandwidth: Up to 448 GB/s

Memory Width: 256 bit

Connectors 4x DP

One 6-pin auxiliary power connector

Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to

Dual-Link DVI adapters available as accessories.

Maximum Resolution 7680x4320 @ 60Hz

Display Outputs1 4x DP

Supported Graphics APIs DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX A4500 20GB Form Factor

Graphics

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Graphics Controller NVIDIA® RTX A4500 Graphics

GPU: 7168 NVIDIA® CUDA® Parallel Processing Cores

Power: 200 Watts Cooling: Active

20GB GDDR6 memory Memory

Memory Bandwidth: Up to 640 GB/s

Memory Width: 320 bit

Connectors 4x DP

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to

Dual-Link DVI adapters available as accessories.

Maximum Resolution 7680x4320 @ 60Hz

Display Outputs1 4x DP

Supported Graphics APIs DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL™, Java, Python, and Fortran

Technical Specifications - Graphics

Available Graphics
Drivers

Windows 11 Windows 10 Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

AMD Radeon™ Pro W5500 Form Factor

8GB Graphics

Factor Single slot, full-height, 9.5" length

Graphics Controller Radeon™ Pro W5500

Power: 120 Watts

Cooling Solution: Active Fan Heatsink

Memory 8GB GDDR6

Maximum Resolution DisplayPort™ 1.4:

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz- supports Multi-Stream Transport (MST)

Display Outputs DisplayPort™ 1.4 Connectors

FreeSync support

Shading Architecture

Full Microsoft DirectX 12 Shader Model 5.1

Supported Graphics APIs DirectX® 12 (12_1)

OpenGL[®] 4.6 OpenCL[™] 2.0 Vulkan[™] 1.1

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T1000 4GB Graphics

Form Factor

Low-Profile Single Slot (6.13"

Length)

Graphics Controller

NVIDIA® T1000 4GB Graphics

Power: 50 Watts

Cooling: Active Fan Heatsink

Memory

Maximum Resolution

4GB GDDR6 memory

tion DisplayPort™ 1.4a:

- up to 4x 5210 x 3200 x 24 bpp @ 60Hz, uncompressed

- 7680 x 4320 x 36 bpp @ 60Hz, compressed - supports Multi-Stream Transport (MST)

Display Output

4 mDP (Mini DisplayPort™) 1.4 Connectors

Shading Architecture
Supported Graphics APIs

DirectX®12.1

Shader Model 5.1

OpenGL® 4.6 OpenCL™ 1.2 Vulkan™ 1.2

Technical Specifications - Graphics

Available Graphics Drivers Windows 11 Windows 10

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html



Technical Specifications - Graphics

AMD Radeon™ RX 6700 XT Form Factor Dual slot, Full Length (254mm L x 38mm W x 108.65mm H)

Graphics Controller AMD Radeon™ RX 6700 XT Graphics

GPU: 2560 Navi2 Stream Processors

Memory: 12GB GDDR6

Power: 230 Watts, Standard graphics 8pin + 6pin auxiliary power

Cooling: Active, Dual Axial fan

Bus Type PCI Express 4.0 x16

Connectors 3DP 1.4 + HDMI 2.1 Outputs

Maximum Resolution DisplayPort™ 1.4 with DSC:

- up to 4x 5210 x 3200 x 24 bpp @ 60Hz, uncompressed

- up to 7680 x 4320, compressed

Display Outputs 3 DP + 1 HMDI

Shading Architecture Microsoft DirectX 12 Shader Model 6.1

Supported Graphics APIs OpenGL 4.6

DirectX 12 Feature Level 12_1

Vulkan 1.1 OpenCL 2.2

Available Graphics

Drivers

Windows 11

Linux® 64-bit (selected distributions)

Typically, latest drivers will be available from amd.com

Notes This is a Prosumer or Consumer graphics card, and not a Professional

graphics card. As such, it does not have formal professional application validation, but is intended per AMD to function properly for game development, real-time engine, and many prosumer application workloads. Customers using Prosumer or Consumer graphic cards are likely to experience higher acoustics in comparison with Professional graphic cards. The higher acoustics observed with non-professional graphics is expected, as HP Workstations' designs do not have control in

this area.

NVIDIA® RTX A2000 6GB

Graphics

Form Factor Dimensions: 2.713" H x 6.6" L

Dual slot, half-height

Weight: 295 grams (without extender)

Graphics Controller NVIDIA® RTX A2000 Graphics Card

Power: 70W Cooling: Active

Bus Type PCI Express 4.0 x16 **Memory** Size: 6GB GDDR6

Memory Bandwidth: Up to 288 GB/s

Memory Width: 192-bit

Connectors 4x mini-DisplayPort™ 1.4a

Maximum Resolution Up to 4x 5120 x 2880 x 24bpp @ 60Hz

Architecture NVIDIA® Ampere™

Technical Specifications - Graphics

Supported Graphics APIsCUDA, OpenCL™ 1.xAvailable GraphicsMicrosoft Windows 11

Drivers Microsoft Windows 10

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Linux® 64-bit (selected Enterprise distributions)

Notes 1. RTX A2000 offered as Factory Configured Option does not include

a video cable adapter. Video cable adapters must be ordered

separately as AMO:

a. 2MY05AA - HP Single miniDP-to-DP Adapter Cable

b. 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

Two mDP-to-DP adapters are included with the RTX A2000 when it is ordered as an AMO kit.

AMD Radeon™ Pro W5700 Form Factor Full-Height Dual Slot (10.5" Length)

8GB Graphics

Graphics Controller Radeon™ Pro W5700

Power: 210 Watts

Cooling Solution: Active Fan Heatsink

Memory 8GB GDDR6

Maximum Resolution DisplayPort™ 1.4:

up to 4x 5120 x 2880 x 24 bpp @ 60Hzsupports Multi-Stream Transport (MST)

Display Output 4 DisplayPort™ 1.4 Outputs

FreeSync support

Supported Graphics APIs DirectX® 12 (12_1)

OpenGL[®] 4.6 OpenCL[™] 2.0 Vulkan[™] 1.0

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html



Technical Specifications - Optical and Removable Storage

HP 9.5mm Slim DVD Writer **Description** 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types DVD+R

DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Access Times Full Stroke DVD < 200 ms (seek)

Full Stroke CD < 200 ms (seek)

Maximum Data Transfer

Rates

CD ROM Read CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions noncondensing)

Relative Humidity 10% to 80% **Maximum Wet Bulb** 84° F (29° C)

Temperature

Operating Systems

Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit,

Windows Vista Business 64*, Windows 2000.

Linux®.

Kit Contents HP SATA DVD Writer drive, installation guide.

Approvals USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport

Specification Rev. 1.0,

Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.



Technical Specifications - Optical and Removable Storage

HP 9.5mm Slim DVD-ROM Description 9.5mm height, tray-load Drive Mounting Opiontation Sither hardward or worth

Mounting Orientation Either horizontal or vertical

Interface TypeSATA / ATAPIDimensions (WxHxD)128 x 9.5 x 127mm

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB

Double layer: Up to 8.5 GB

Access Times DVD-ROM Single Layer < 110 ms (typical)

CD-ROM Mode 1 < 110 ms (typical)
Full Stroke DVD < 230 ms (typical)
Full Stroke CD < 220 ms (typical)

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC – <800mA typical, < 1600 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions noncondensing) Relative Humidity 10% to 80% Maximum Wet Bulb 84° F (29° C)

Temperature

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Operating Systems Windows 11, Windows 10, Windows 7 Professional 64-bit, **Supported**

Windows Vista Business 64*, Windows 2000.

Linux®.

Kit Contents 9.5mm Slim DVD-ROM Drive, slim SATA data/power cable, installation

quide

Approvals USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport

Specification Rev. 1.0,

Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.



Technical Specifications - Controller Cards

HP Thunderbolt™ 3/USB4 Data Transfer Rate
PCIe 3-Single-port I/O Devices Supported

Card

Data Transfer RateSupports up to 40 Gb/s* 40,000 Mb/s)Devices SupportedThunderbolt™ certified devices

Bus TypePCIe card, full height PCIe slotPortsOne USB4 Type-C® connector (Rear)

Internal Connectors Two wire-to-board-connectors

System Requirements Windows 10/11, Intel® i5 series or higher processor, available on PCIe

slot4.

20% to 80%

Temperature - Operating 50° to 131° F (10° to 55° C) **Temperature - Storage** -22° to 140° F (-30° to 60° C)

Relative Humidity -

Operating Compliances

FCC Part 15B, cULus, CE Mark EN55032B/EN55024, Taiwan BSMI, Korea KCC

Operating Systems Windows 11 Supported Windows 10

Kit Contents HP Thunderbolt™ 3/USB4 PCIe 3 Single-port I/O Card, Flex IO wire-to-board

module, One full height and One Low-Profile brackets, One power cable, One DisplayPort™ and GPIO (General-Purpose Input/Output) cable,

Installation documentation and warranty card.

*Maximum speed requires DisplayPort™ and PCIe aggregation.

Technical Specifications - Networking and Communications

Integrated Intel® I219LM Connector
PCIe GbE Controller Cabling
(Intel® vPro® with Intel®

AMT 15.0)

Connector RJ-45

Cabling Twin Axial Cabling up to 10m

Controller Intel® I219LM GbE platform LAN connect networking controller

Memory 3 KB Tx and 3KB Rx FIFO packet buffer memory

Data Rates Supported 10/100/1000 Mbps

Compliance 802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i, 802.3u,

802.3z

Bus Architecture PCI Express and SMBus

Data Transfer Mode PCIe-based interface for active state operation (S0 state) and SMBus for

host and management traffic (Sx low power state)

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support Yes

Network Transfer Mode Full-duplex; Half-duplex (not supported for the 1000BASE-T transceiver)

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 10 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 100 Mbps 1000BASE-T (full-duplex) 1000 Mbps

Management Capabilities vPro®, WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, ACPI,

Advanced cable diagnostic, loopback modes,

AMT 15.0 support, Circuit Breaker, VLAN, Multicast Listener Discovery

(MLD)

HP 1-Port 1GbE Flex IO NIC

Connector RJ-45

Cabling 1GbE over Category 5e (or better) up to 100m

Controller Realtek RTL8153

Data Rates Supported 10/100/1000 Mbps

Compliance 802.3 (LAN)

802.3u (100BASE-TX) 802.3ab (1000BASE-T) 802.3x (Ethernet Flow Control)

802.1Q (Virtual LAN)

802.3az (Energy Efficient Ethernet)

Bus Architecture USB

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support Yes

Network Transfer Mode Full-duplex; Half-duplex

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 10 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 100 Mbps 1000BASE-T (full-duplex) 1000 Mbps

Operating Temperature 32° to 131° F (0° to 55° C)

Dimensions (HxW) 1.5 in x 1.5 in. x 0.75 in (3.81 cm x 3.81 cm x 1.9 cm)

Technical Specifications - Networking and Communications

Operating System Driver Windows 11

Support

Windows 10

Linux®

HP 10GbE SFP+ SR

Transceiver

Operating Temperature

Operating Humidity Dimensions (HxWxD)

Kit Contents

32°F to 113°F (0°C to 45°C)

0% to 85%, noncondensing 0.47 x 0.54 x 2.19 inches

HP 10GbE SFP+ SR Transceiver

Intel® X550-T2 2-Port **10GbE NIC**

Connector 2 RJ-45

Cabling 10GbE: Cat6a (or better) up to 100m

5GbE and below: Cat5e (or better) up to 100m

Controller Intel® Ethernet Controller X550

Network Transfer Rates

Supported

10GbE, 5GbE, 2.5GbE, 1GbE, 100MbE

Data Path Width PCIe Gen3x4 **Power Requirement** 11.2W (typical)

Operating Temperature 32° to 131° F (0° to 55° C) **Dimensions** (HxW) 5.1 x 2.7 in (without brackets)

Operating System Driver Windows 11

Support

Windows 10 Linux®

Kit Contents Intel® X550-T2 2-Port 10GbE NIC with standard height bracket

attached

Low-profile bracket **Product Literature**

Aquantia® AQN-108 1-**Port 5GbE NIC**

Connector 1 RJ-45

Cabling Cat5e (or better) up to 100m

Controller Aguantia® AQC108

Network Transfer Rates

Supported

5Gbe, 2.5GbE, 1GbE, 100MbE

Data Path Width PCIe Gen3x1 **Power Requirement** 3.5W (typical)

32° to 131° F (0° to 55° C) **Operating Temperature**

Dimensions (HxW) 3.72 x 3.18 inches (without brackets)

Operating System Driver Windows 11

Support

Windows 10

Linux®

Kit Contents Aquantia AQN-108 1-Port 5GbE NIC with standard height bracket

attached

Low-profile bracket

Product Literature

Connector 2 RJ-45

Technical Specifications - Networking and Communications

Intel® I350-T2 2-Port **1GbE NIC**

Cabling Cat5e (or better) up to 100m Controller Intel® Ethernet I350 Controller 1GbE, 100MbE, 10MbE

Network Transfer Rates

Supported

Data Path Width PCIe Gen2.1x4 **Power Requirement** 4.4W (typical)

32° to 131° F (0° to 55° C) Operating Temperature

Dimensions (HxW) 2.75 x 5.5 inches (without brackets)

Operating System Driver Windows 11

Support

Windows 10 Linux®

Kit Contents Intel® 1350-T2 2-Port 1GbE NIC with standard height bracket attached

> Low-profile bracket **Product Literature**

Intel® I350-T4 4-Port **1GbE NIC**

4 RJ-45 Connector

Cabling Cat5e (or better) up to 100m Controller Intel® Ethernet I350 Controller

Network Transfer Rates

Supported

1GbE, 100MbE, 10MbE

Data Path Width PCle Gen2.1x4 **Power Requirement** 5W (typical)

Operating Temperature 32° to 131° F (0° to 55° C)

Dimensions (HxW) 2.75 x 5.5 inches (without brackets)

Operating System Driver Windows 11

Support

Windows 10

I inux®

Kit Contents Intel® I350-T4 4-Port 1GbE NIC with standard height bracket attached

Low-profile bracket

Product Literature

Intel® I225-T1 1-Port 2.5GbE NIC

*Planned to be available in Q3,2021

Connector 1 RJ-45

Cabling Cat5e (or better) up to 85m Controller Intel® Ethernet I225 Controller

Network Transfer Rates

Supported 2.5GbE, 1GbE, 100MbE, 10MbE

Data Path Width PCIe Gen3.1x1 2W (typical) **Power Requirement**

Operating Temperature 32° to 158° F (0°C to 70°C)

Operating System Driver

Support

Windows 11 Windows 10 Linux®

Kit Contents

Intel® I225-T1 1-Port 2.5GbE NIC with standard height bracket

attached

Low-profile bracket

Product Literature

Technical Specifications - Networking and Communications

Intel® Wi-Fi 6 AX201 802.11ax, BT 5.1, M.2 **WLAN Standards** 802.11-2016 and select amendments (selected feature coverage)

802.11 a,b,d,e,g,h,i,k,n,r,u,v,w,ac,ax;

Fine Measuermant based on 802.11-2016

Antenna 2x2 Dual-Band

Bluetooth Standards 5.1

Operating Temperature 32° to 176° F (0° to 80° C)

InterfaceM.2 CNVio2DimensionsM.2 2230Kit ContentsNot Available

NOTE: Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

Z2 G8 Tower Bezel w/ Dust Filter option

Part Number Overview

141L3AA

Workstations are deployed in a variety of different ways and in different environments, from under a desk to manufacturing floors. HP Workstations designed a dust filter option to further protect the system against the ingress of dust and other particles over the life of the system. Test have shown a reduction of dust ingress of up to 32% for the HP Z2 Tower G8 Workstation platform and is cleanable and serviceable by customers. There is also a BIOS setting that will warn customer when it is time to check and clean their filters.

Cleaning and servicing the dust filter

- After removing the filter from the system bezel (dust filter can be removed without the use of tools from the front bezel), either blow it with and wash with water or use a delicate duster (feather duster) to brush off the filter then rinse it with water.
- 2. Allow the filter half a day to dry at room temperature (25C at 30%-50% humidity)
- 3. Temperature of water can be 0-70C, due to the dust filter meeting the SQTM 70C humidity test. Suggested water temperature for best user experience is 0-50C.
- 4. Normal tap water (and most other types of water) can be used to rinse the filter. Any type of corrosive liquid is restricted.

Enabling the Check Filter warning in the BIOS:

- Customers must enable the BIOS setting once they receive their filter.
- 2. To enable, do the following once you see the boot screen for your system: F10 > Advanced > Built-In Device Options > Dust Filter
- 3. Select to enable the Dust Filter replacement reminder, which can be set for 15, 30, 60, 90, 120, or 180 days. The Reminder will show during POST after the reminder timer has expired.

4.

NOTE: customers who anticipate more dust ingress in their environments should set the reminder for a shorter window. Customers anticipating longer ingress can set the reminder for a longer window.

BIOS Warnings

Large enterprise customers deploying multiple systems can centrally enable/control the BIOS warning using the WMI/BCU tool remotely to set the options below:

Dust Filter

- Disable*
- Enable



Technical Specifications - Networking and Communications

Dust Filter Reminder (Days)

15, 30, 60*, 90, 120, and 180

Z2 G8 Tower Dust Filter (Filter Only)

Part Number

141L2AA

This is intended to be a replacement filter for the HP Z2 Tower G8 Workstation in the event that the original filter would need to be replaced.

HP Z2 Tower PCIe Card Holder/Blower Kit **Part Number**

2B1D4AA

Features

This card holder/blower kit is required to enable added mechanical stability when configuring select graphics cards on the HP Z2 Tower G8 Workstation.

The kit enables added mechanical stability when configuring:

- 2x AMD Radeon™ Pro WX 3200 4GB
- 1x AMD Radeon™ Pro W5500 8GB
- 1x AMD Radeon™ Pro W5700 8GB
- 2x NVIDIA® Quadro® P400
- 2x NVIDIA® T1000 4GB
- 1x NVIDIA® RTX® A5000 24GB
- 1x NVIDIA® RTX® A4000 16GB

NOTE: If one of the above graphics cards is configured with the Z2 G8 TWR at time of purchase or the 700W chassis is configured, the Card Holder/Blower is automatically included.

 If one of the above graphics cards is added as an aftermarket option, the Card holder/Blower Kit (2B1D4AA) is required, as a separate purchase, for installation of the graphics card.



Technical Specifications – Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode.
 Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
 - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
 - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
 - 2 red + 4 white BIOS recovery is in progress
 - 3 red + 2 white Memory could not be initialized
 - 3 red + 3 white Graphics adaptor could not be found
 - 3 red + 4 white Power supply failure / not connected
 - 3 red + 5 white Processor not installed
 - 3 red + 6 white Current processor does not support an enabled feature
 - 3 red + 7 white Computer cover has been removed since last system startup
 - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
 - 4 red + 3 white System internal temperature has exceeded its threshold
 - 5 red + 2 white System controller firmware is not valid
 - 5 red + 3 white System controller detected BIOS is not executing
 - 5 red + 4 white BIOS could not complete initialization / PCA failure
 - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
 - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal
- Blue Pull Tabs, and Quick Release Latches for easy Identification



Summary of Changes

Date of change:	Version History:		Description of change:
May 3, 2021	From v1 to v2	Changed	Format page 2
May 13, 2021	From v2 to v3	Added	Intel Xeon W-1300 series
May 26, 2021	From v3 to v4	Changed	SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS and
			Social and Environmental Responsibility sections
June 11, 2021	From v4 to v5	Changed	Hard Drive Controllers section
July 15, 2021	From v5 to v6	Changed	Memory section
August 1, 2021	From v6 to v7	Changed	Graphics section
August 11, 2021	From v7 to v8	Changed	Social and Environmental Responsibility section
September 1, 2021	From v8 to v9	Changed	Processors Matrix, Memory, Optical and Removable Storage
			sections
September 20, 2021	From v9 to v10	Changed	Graphics section
October 1, 2021	From v10 to v11	Changed	Graphics, Optical and Removable Storage sections
December 1, 2021	From v11 to v12	Changed	Operating Systems, Optical and Removable Storage, Graphics and
			Input Devices sections
December 3, 2021	From v12 to v13	Changed	SOFTWARE AND SECURITY section
December 15, 2021	From v13 to v14	Changed	OPERATING SYSTEM and Social and Environmental Responsibility
			sections
January 1, 2022	From v14 to v15	Changed	Graphics, Memory, OPERATING SYSTEM,
			NETWORKING/COMMUNICATIONS and Application Software sections
February 1, 2022	From v15 to v16	Changed	Graphics, Networking and Communications sections
March 1, 2022	From v16 to v17	Changed	Hard Drive Controllers and Other Hardware sections
October 1, 2023	From v17 to v18	Changed	Overview section
December 1, 2023	From v18 to v19	Changed	Social and Environmental Responsibility section
June 12, 2024	From v19 to v20	Changed	Software section



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